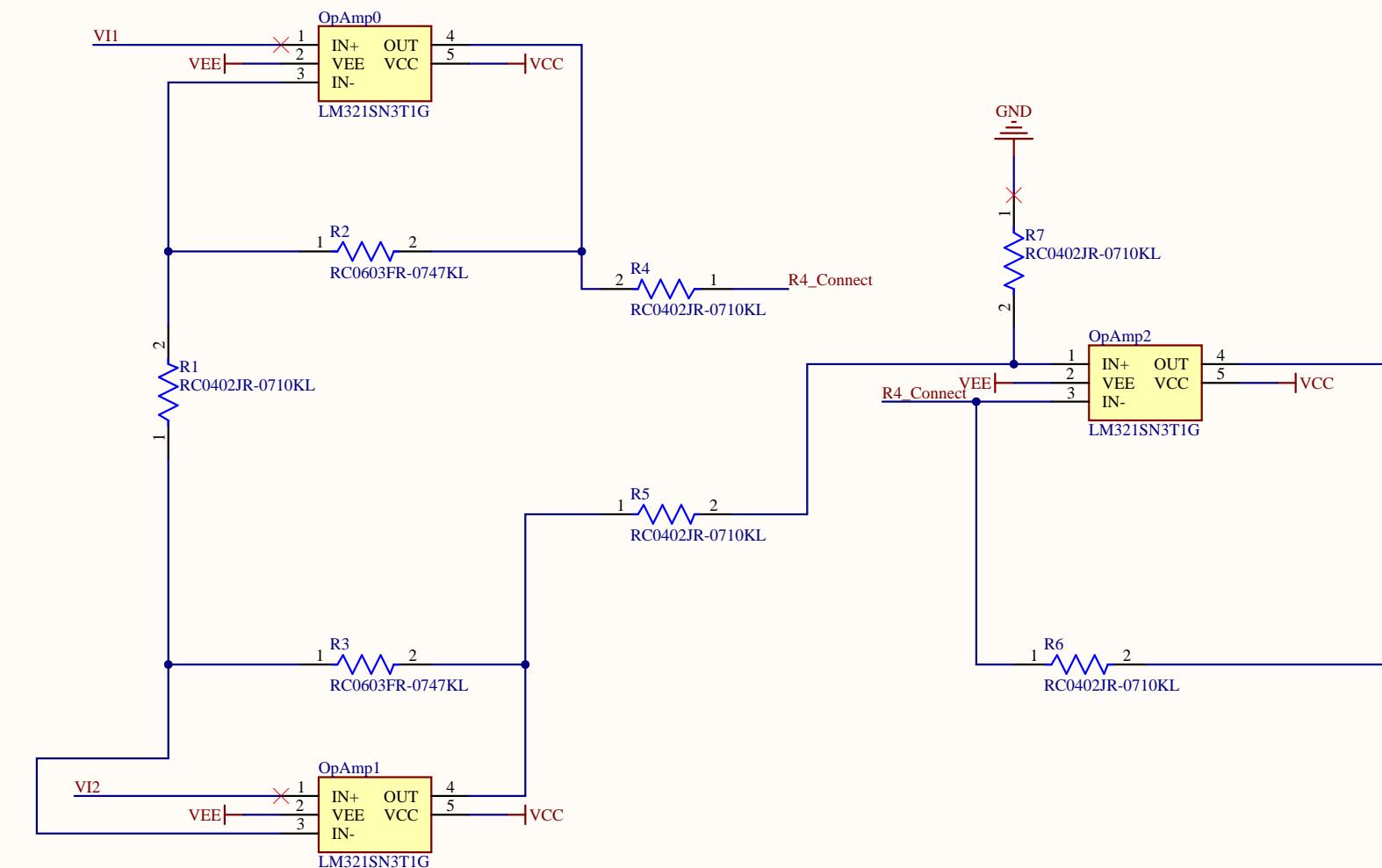


A



B

A

B

C

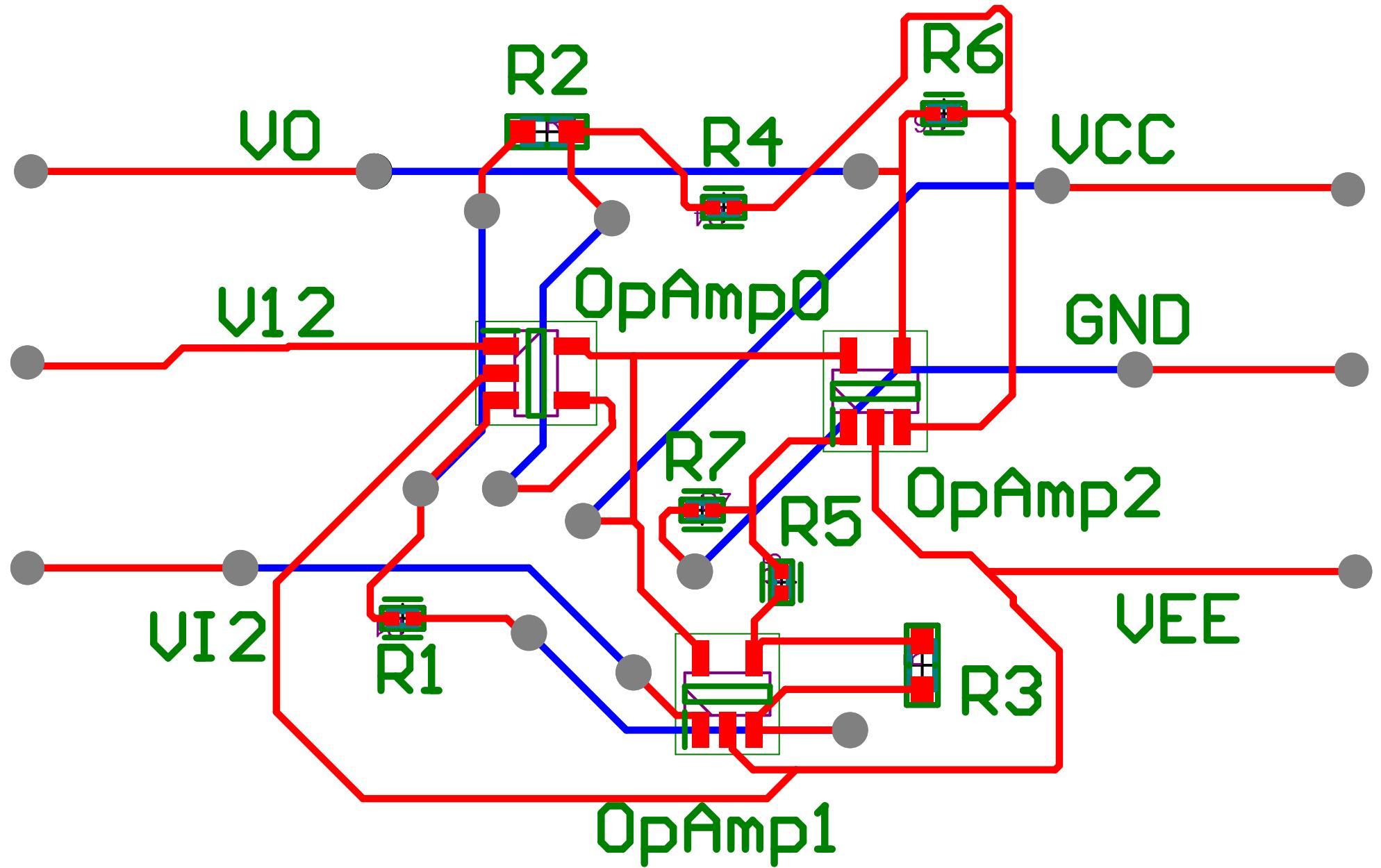
C

D

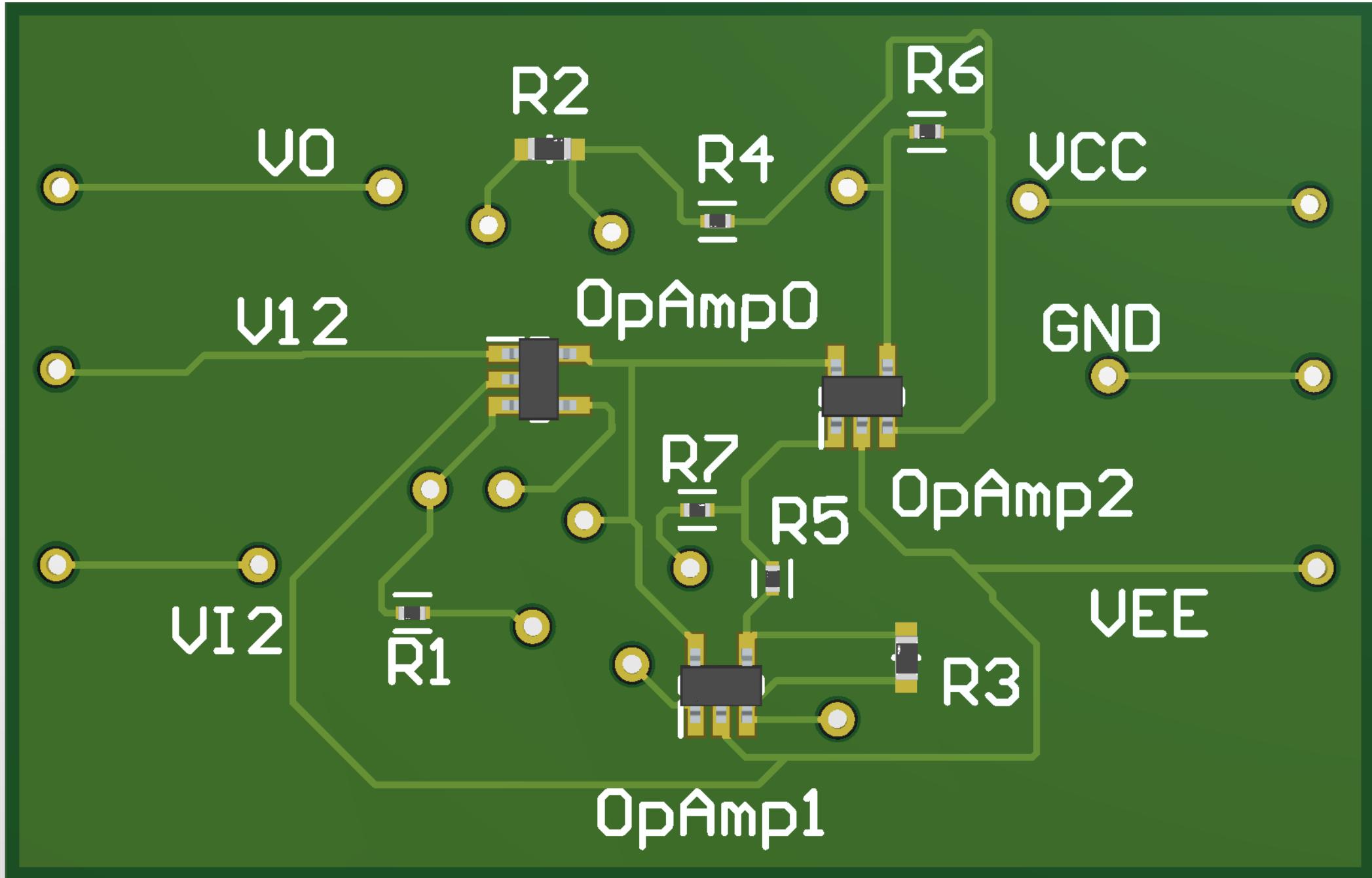
D

Title
Electronics PCB Extra Credit

Size	Number	Revision
A		
Date: 11/22/2025	Sheet of	
File: C:\Users\...\Electronics_Instrumentation.SchDoc	Download By:	Ezra Manansala



Board Stack Report



Board Stack Report

Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Overlay		0mil	
2		Top Solder	Solder Resist	0.4mil	3.5
3	■ ■ ■ ■	Top Electric		1.4mil	
4		Dielectric 2	PP-006	2.8mil	4.1
5		MidTop Electric	CF-004	1.378mil	
6		Dielectric 1	FR-4	12.6mil	4.8
7		MidBot Electric	CF-004	1.378mil	
8		Dielectric 3	PP-006	2.8mil	4.1
9	■ ■ ■ ■	Bottom Electric		1.4mil	
10		Bottom Solder	Solder Resist	0.4mil	3.5
11		Bottom Overlay		0mil	
Height : 24.556mil					

Line #	Name	Description	Designator	Revision ID	Revision State	Revision Status	Quantity	Manufacturer 1	Manufacturer Part Number 1	Manufacturer Lifecycle 1	Supplier 1	Supplier Part Number 1	Supplier Unit Price 1	Supplier Subtotal 1
	LM321SN3T1G	Integrated Circuit	OpAmp0, OpAmp1, OpAmp2		Not managed		3							
	RC0402JR-0710KL	RES 10K OHM 5% 1/16W 0402	R1, R4, R5, R6, R7	OMP-2002-07915-3	Released	Up to date	5	Yageo Group	RC0402JR-0710KL	Volume Production	DigiKey	311-10KJRDKR-ND	0.006	0.06
	RC0603FR-0747KL	RES SMD 47K OHM 1% 1/10W 0603	R2, R3	OMP-1659-00055-2	Released	Up to date	2	Yageo Group	RC0603FR-0747KL	Volume Production	DigiKey	311-47.0KHRCR-ND	0.006	0.06